

ABSTRACT OF THE DISCLOSURE

The invention relates to a photosensitive adhesive composition of the polymerisable resin type, the hardening of which occurs by means of polymerisation and/or reticulation, characterised in comprising: - initiating means for at least one chain polymerisation reaction to guarantee the hardening of said composition and a sufficient quantity of at least one bifunctional monomer, comprising a photolabile centre with at least one photolabile entity and at least two polymerisable units, connected by covalent skeletons to said photolabile centre and located away from the cleavage sites of said photolabile centre, such that said composition loses the integrity and adhesivity thereof under the influence of a reticulating radiation causing the cleavage of the photolabile sites. The composition is particularly of application in dentistry.

